2020-05-07 Rev.2.0

RD Number: RD085

RD Title: TC78H611FNG Evaluation circuit BOM

Item No.	Designator	Quantity	Value	Part Number	Manufacturer	Description	Package	Not Mount
1	IC1	1	TC78H611FNG	TC78H611FNG	TOSHIBA	Motor driver IC	TSSOP16	
2	C_VCC	1	0.1µF 50V	—	—	Chip capacitor	3.2mm×1.6mm	
3	C_VM1	1	10µF 50V	—	—	Electrolytic capacitor		
4	C_VM2	1	0.1µF 50V	—	—	Chip capacitor	3.2mm×1.6mm	
5	C_AO1	0	Not mount	—	—	Chip capacitor	3.2mm×1.6mm	✓
6	C_AO2	0	Not mount	—	—	Chip capacitor	3.2mm×1.6mm	✓
7	C_BO1	0	Not mount	—	—	Chip capacitor	3.2mm×1.6mm	✓
8	C_BO2	0	Not mount	—	—	Chip capacitor	3.2mm×1.6mm	✓
9	CN1	0	Connector	—	—	CONN HEADER VERT 4POS		✓
10	CN2	1	Connector	—	—	CONN HEADER VERT 2POS		
11	CN3	1	Connector	—	—	CONN HEADER VERT 2POS		
12	IN1A	1	Check terminal	—	—	Check terminal for logic		
13	IN2A	1	Check terminal	—	—	Check terminal for logic		
14	IN1B	1	Check terminal	—	—	Check terminal for logic		
15	IN2B	1	Check terminal	—	—	Check terminal for logic		
16	/STBY	1	Check terminal	—	—	Check terminal for logic		
17	AO1	1	Check terminal	—	—	Check terminal for logic		
18	AO2	1	Check terminal	—	—	Check terminal for logic		
19	BO1	1	Check terminal	—	—	Check terminal for logic		
20	BO2	1	Check terminal	—	—	Check terminal for logic		
21	VCC	1	Check terminal	—	—	Check terminal for logic		
22	VM	1	Check terminal	—	—	Check terminal for logic		
23	GND1	1	Check terminal	—	—	Check terminal for logic		
24	GND2	1	Check terminal	—	—	Check terminal for logic		
25	GND3	1	Check terminal	—	—	Check terminal for logic		

26	GND4	1	Check terminal	—	—	Check terminal for logic		
27	SW1	1	DIP Switch	—	—	DIP Switch 5P		

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